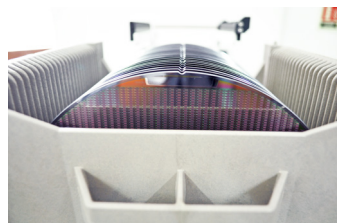


VERTICAL BATCH TRANSFER & ALIGNER

VB200A

VB200A



FACILITY REQUIREMENTS

100/240v ac – 50-60Hz – 2.2A

SPECIFICATIONS (MM)

L 630 x W 294 x H 542 mm



DESCRIPTION

The Vertical Batch Transfer and Notch Alignment machine (VB200A) is a single stage, automated tool that can transfer a batch of 200mm wafers between semi-standard carriers and align a batch of 200mm wafers by the notch.

Wafers are always handled on the edge and detection sensors check for wafer safety during the transfer and alignment processes. The VB200A provides true ESD protection for wafers and carriers.

The angle of alignment can be easily selected through the user-friendly keypad.

VB200A provides multiple functions within an incredibly small footprint and at an extremely competitive price. For further info on VB200A please contact your local EMU representative or EMU directly.



RECIF TECHNOLOGY

This tool has been designed under license from Recif Technologies using the same design principles, materials and kinematics as were used in the original equipment and wafer fabs around the world.

SUPPLIERS TO THE SEMICONDUCTOR INDUSTRY

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100/125MM WAFER HANDLING
150MM WAFER HANDLING
200MM WAFER HANDLING
VACUUM HANDLING SYSTEMS
RETICLE HANDLING
N2 PURGE SYSTEMS
WAFER CARRIERS
CARRIER HANDLES